Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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SD53

Low profile shielded power inductors

Product description

- Octagonal shape utilizes board space
- Shielded drum core
- Inductance range from 1.1 uH to 100 uH
- Current range from 0.44 A to 4.8 A
- 5.7 mm x 5.2 mm footprint surface mount package in a 3.0 mm height
- Ferrite core material
- Halogen free, lead free, RoHS compliant

Applications

- Desktop computers
- Notebook and laptop regulators
- LED and White LED drivers
- Digital cameras, media devices
- Battery power systems

Environmental Data

- Storage temperature range (component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (Ambient plus self temperature rise)
- Solder reflow temperature: J-STD-020D compliant

Pb HALOGEN HF FREE RoHS

Powering Business Worldwide

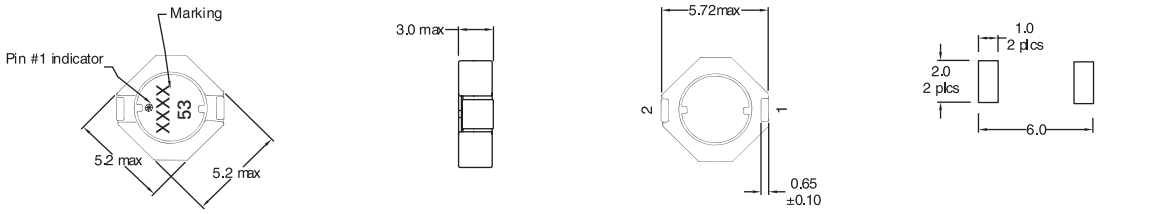
Product Specifications

Part Number[5]	OCL1 (µH) ±20%	Part marking	I_{rms}[2] (A)	I_{sat}[3] (A)	DCR (Ω) typical @ 20 °C	DCR (Ω) maximum @ 20 °C	K-factor[4]
SD53-1R1-R	1.10	A	3.25	4.80	0.017	0.020	48
SD53-2R0-R	2.00	B	2.64	3.30	0.023	0.027	35
SD53-3R3-R	3.30	C	2.26	2.60	0.029	0.034	28
SD53-4R7-R	4.70	D	2.01	2.10	0.039	0.045	21
SD53-6R8-R	6.80	E	1.65	1.85	0.059	0.068	20
SD53-100-R	10.0	F	1.41	1.40	0.077	0.090	15
SD53-150-R	15.0	G	1.10	1.10	0.122	0.142	12
SD53-220-R	22.0	H	0.81	0.94	0.179	0.208	10
SD53-330-R	33.0	I	0.75	0.76	0.221	0.257	8
SD53-470-R	47.0	J	0.64	0.64	0.303	0.352	7
SD53-680-R	68.0	K	0.52	0.58	0.452	0.525	6
SD53-101-R	100	L	0.44	0.45	0.689	0.801	5

1. 1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.1 Vrms, 0.0 Adc.
2. Irms: DC current for an approximate ΔT of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125 °C under worst case operating conditions verified in the end application
3. Isat: Peak current for approximately 30% rolloff @ 25 °C.
4. K-factor: Used to determine B p-p for core loss (see graph). B p-p = K*L*ΔI, B p-p(mT), K: (K factor from table), L: (Inductance in uH), ΔI (Peak to peak ripple current in Amps).
5. Part Number Definition: SD53-xxx-R
   SD53 = Product code and size; -xxx = Inductance value in uH; R = decimal point;
   If no R is present then third character equals the number of zeros.
   -R suffix = RoHS compliant.

Dimensions (mm)

RECOMMENDED PCB LAYOUT

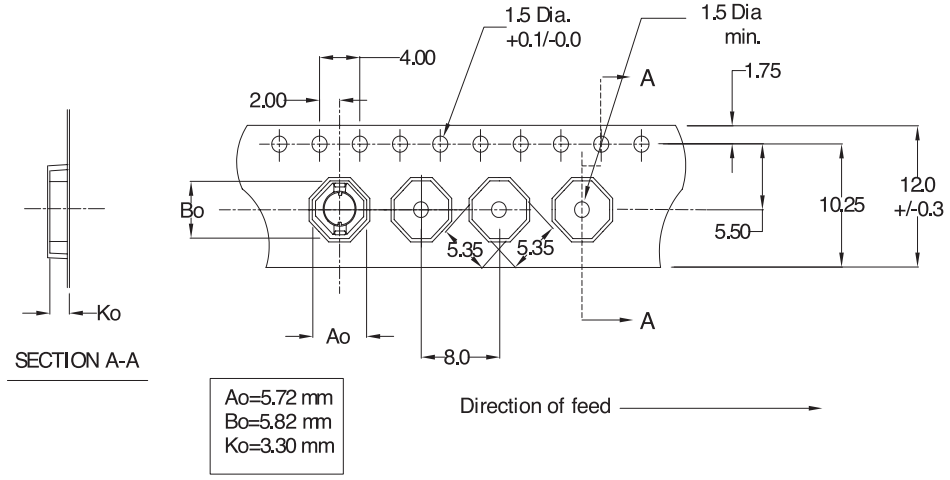


Part Marking: Line 1: (1st digit= inductance value per Part Marking Designator); (2nd digit= Bi-weekly production date code); (3rd digit= Last digit of the year produced), (4th digit= Internal manufacturing code). Line 2: 53=product size code)

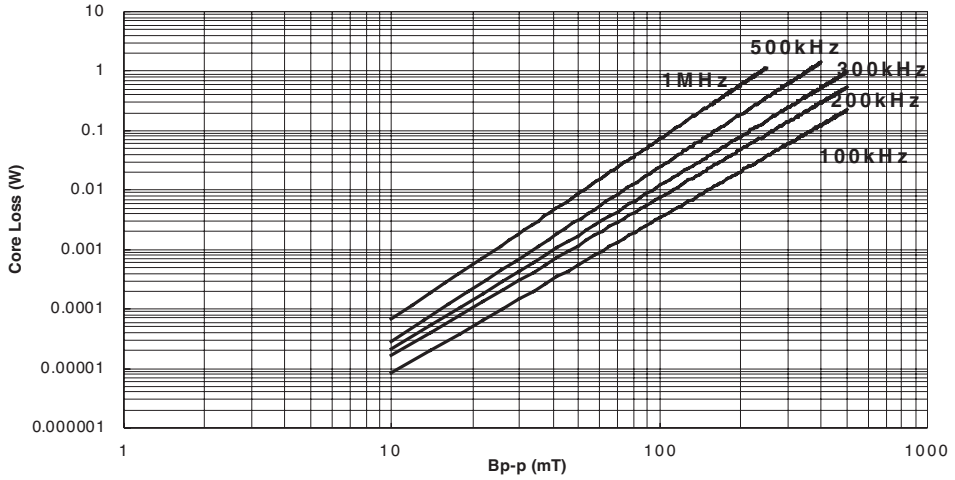
Do not route traces or vias underneath the inductor

Packaging information (mm)

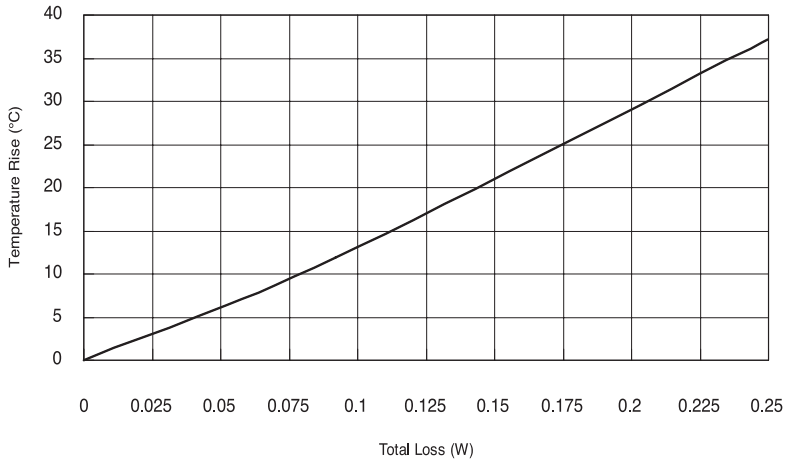
Parts packaged on 13" diameter reel, 2,600 parts per reel.



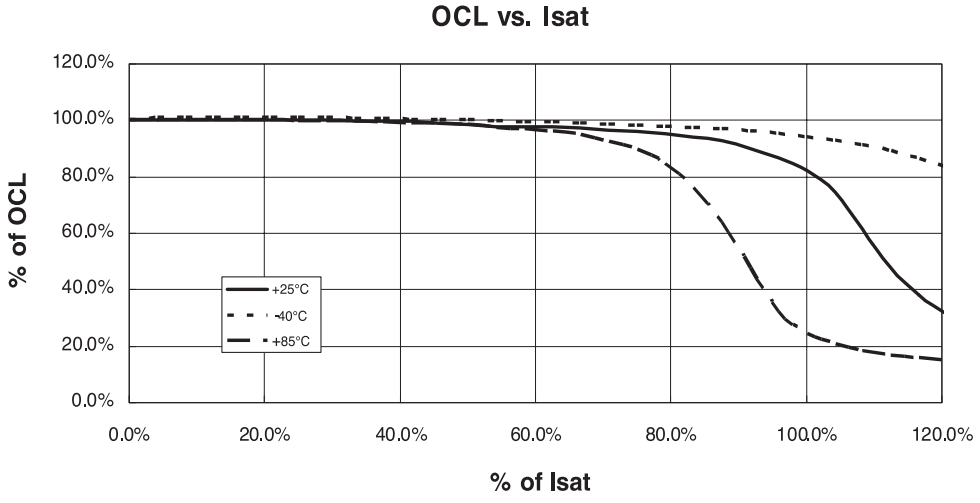
Core loss vs. Bp-p



Temperature rise vs. total loss



Inductance characteristics



Solder reflow profile

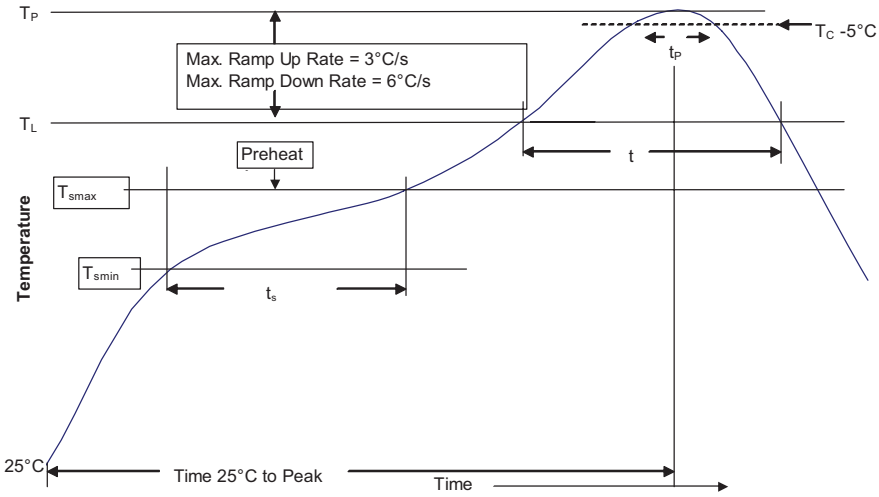


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. (T_{smin})	100°C	150°C
	• Temperature max. (T_{smax})	150°C	200°C
	• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p		3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L) Time at liquidous (t_L)		183°C 60-150 Seconds	217°C 60-150 Seconds
Peak package body temperature (T_P)*		Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)		20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})		6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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Printed in USA
Publication No. 4149
November 2015

Powering Business Worldwide